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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Divisional Application of:

Akihiro SASAKI et al.

Serial No. 10/012,462

Filed: December 12, 2001

For: PHOTORESISTIVE RESIN
COMPOSITION, PATTERNING
METHOD, AND ELECTRONIC
COMPONENTS

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Atty. Docket No.: TSUK 0004
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Group Art Unit: 1756
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Examiner: CHACKO-DAVIS, Daborah
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Date: May 19, 2003
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MAY 2, 2003
TC 1700

AMENDMENT (A)

BOX: FEE AMENDMENT

Assistant Commissioner for Patents
Washington, D. C. 20231

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Sir:

In response to the official Office Action, dated December 19, 2002, please amend the above captioned application as follows:

IN THE CLAIMS:

✓ Please cancel claim 5 without prejudice.

Kindly amend claims 1, 4 and 6, and add new claims 10-12 as follows.

1. (Amended) A photosensitive resin composition comprising an aromatic polyimide precursor, wherein a 10 μ m thick layer of the aromatic polyimide precursor has a light transmittance at a wavelength of 365 nm of at least 1%, and a 10 μ m thick polyimide film made from the resin composition by imidation ring closure and deposited on a silicon substrate has light transmittance at a wavelength of 365 nm of at least 1% and a residual stress of at most 25 MPa,

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